

**Amendments to the Specification:**

Please amend the Specification as follows.

1. Please amend the paragraph beginning on page 6, line 30, and ending on page 7, line 6, as follows:

--In general, if the interface between the grounded housing 107, which is made of a conductive material, and the heat sink 103, which is made of a ceramic material, is located at the boundary between the vacuum and the atmosphere, the heat sink is likely to break or crack. To prevent such damage, a shock absorber 117 is inserted between the heat sink 103 and the housing 107. The shock absorber ~~[[119]]~~ 117 is made of a soft and malleable insulator, such as Teflon. By inserting a shock absorber between the housing (i.e., the conductor) and the heat sink (i.e., the insulator, such as ceramics), the heat sink is protected from breakage even if it is located at the boundary between the vacuum and the atmosphere.--

2. Please amend the paragraph beginning on page 7, line 24, as follows:

--However, in reality, the produced plasma capacity decreases at higher frequency, as is shown in FIG. 4A. If the parasitic capacity of the circuit (that is, the capacity generated between the ground and the conductive passes through which the radio frequency propagates) is, for example, about ~~[[10pH]]~~ 10 pF as indicated by the dashed line C in FIG. 4A, then, the produced plasma capacity becomes almost equal to the parasitic capacity if the applied radio frequency is raised up to 200MHz. This means that the applied radio frequency is wasted on irrelevant activity other than producing plasma. If the radio frequency is further raised, the produced plasma capacity falls below the dashed line C, which means that the parasitic capacity is greater than the produced plasma capacity.--